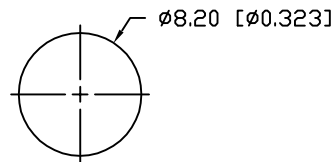


PANEL CUTOUT



ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		574		nm	
FORWARD VOLTAGE		2.2	2.6	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_r=100\mu\text{A}$
AXIAL INTENSITY		170		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	GREEN DIFFUSED				

LIMITS OF SAFE OPERATION AT  $25^\circ\text{C}$

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	200	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	60	mW
DERATE FROM $25^\circ\text{C}$	-1.2	$\text{mW}/^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY		3 SEC. MAX

\*  $t < 10\mu\text{s}$

NOTES:

1. SSL-LX5093SUGD, GREEN LED. TRIM LEADS TO 4mm.
2. SSI-LXR3816, CHROME HOUSING.
3. SSH-LXH4815BSG, BUSHING (NOT SHOWN). INSERT AND CRIMP.
4. ANODE LEAD: LXP-WST24RDT0C, 24 AWG., TINNED OVERCOAT, RED INSULATION. CUT 610mm LONG, STRIP BOTH ENDS 3mm & 9.5mm.
5. CATHODE LEAD: LXP-WST24BLT0C, 24 AWG., TINNED OVERCOAT, BLACK INSULATION. CUT 610mm LONG, STRIP BOTH ENDS 3mm & 9.5mm.
6. CRIMP WIRES TO LED LEADS.

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN= +DECIMAL PRECISION -0.00, MAX= +0.00 -DECIMAL PRECISION

REV.	PART NUMBER
	SSI-LXR3816SUGD600

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T-5mm 574nm AlInGaP GREEN LED PANEL INDICATOR,  
GREEN DIFFUSED LENS, 24.0" WIRE LEADS.

**RELIABILITY NOTE**  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE:
JN			8.10.07
			PAGE: 1 OF 1
			SCALE: N/A